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COMPET 803
MI 851
ENV 1032
ENT 270
TRANS 592
DELACT 232

COVER NOTE

From:	Secretary-General of the European Commission, signed by Mr Jordi AYET PUIGARNAU, Director
date of receipt:	17 December 2019
To:	Mr Jeppe TRANHOLM-MIKKELSEN, Secretary-General of the Council of the European Union
No. Cion doc.:	C(2019) 9121 final, ANNEX
Subject:	ANNEX to Commission Delegated Directive amending Annex II to Directive 2000/53/EC of the European Parliament and of the Council on end-of-life vehicles as regards certain exemptions for lead and lead compounds in components

Delegations will find attached document C(2019) 9121 final, ANNEX.

Encl.: C(2019) 9121 final, ANNEX

www.parlament.gv.at

Brussels, 17.12.2019
C(2019) 9121 final

ANNEX

ANNEX

to

Commission Delegated Directive

amending Annex II to Directive 2000/53/EC of the European Parliament and of the Council on end-of-life vehicles as regards certain exemptions for lead and lead compounds in components

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ANNEX

Annex II to Directive 2000/53/EC is amended as follows:

(1) entry 8(e) is replaced by the following:

8(e). Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	(2)	X

(2) entry 8(f)(b) is replaced by the following:

8(f)(b). Lead in compliant pin connector systems other than the mating area of vehicle harness connectors	Vehicles type-approved before 1 January 2024 and spare parts for these vehicles	X

(3) entry 8(g) is replaced by the following:

8(g)(i). Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	Vehicles type approved before 1 October 2022 and spare parts for these vehicles	X
8(g)(ii). Lead in solders to complete a viable electrical connection between the semiconductor die and the carrier within integrated circuit flip chip packages where that electrical connection consists of any of the following: (i) a semiconductor technology node of 90 nm or larger; (ii) a single die of 300 mm_2 or larger in any semiconductor technology node; (iii) stacked die packages with dies of 300 mm_2 or larger, or silicon interposers of 300 mm_2 or larger.	(2) Valid for vehicles type-approved from 1 October 2022 and spare parts for these vehicles	X

(4) the following entry 8(k) is inserted:

8(k). Soldering of heating applications with 0,5A or more of heat current per related solder joint to single panes of laminated glazings not exceeding wall thickness of 2,1 mm. This exemption does not cover soldering to contacts embedded in the intermediate polymer	Vehicles type approved before 1 January 2024 and spare parts for these vehicles	X(4)

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